

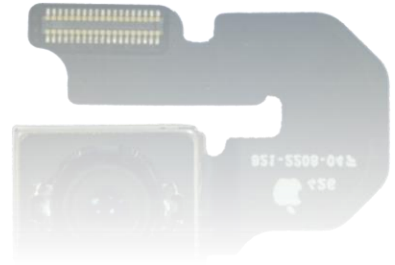
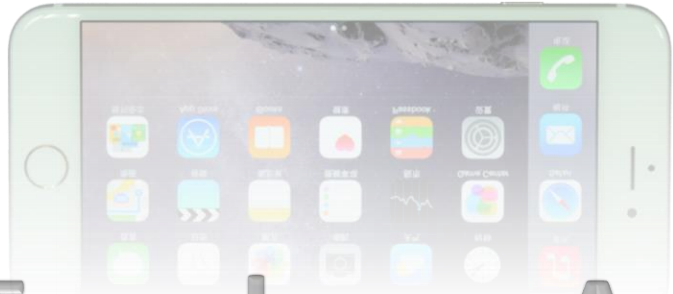
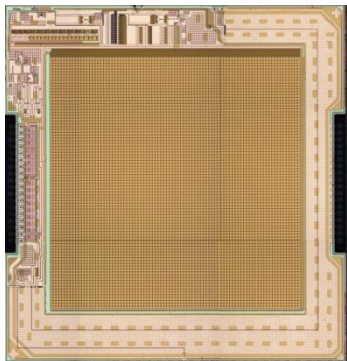
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Teardown Analysis Report

To Know



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